



Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from,Europe,America and south Asia,supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of “Quality Parts,Customers Priority,Honest Operation,and Considerate Service”,our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip,ALPS,ROHM,Xilinx,Pulse,ON,Everlight and Freescale. Main products comprise IC,Modules,Potentiometer,IC Socket,Relay,Connector.Our parts cover such applications as commercial,industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



## Contact us

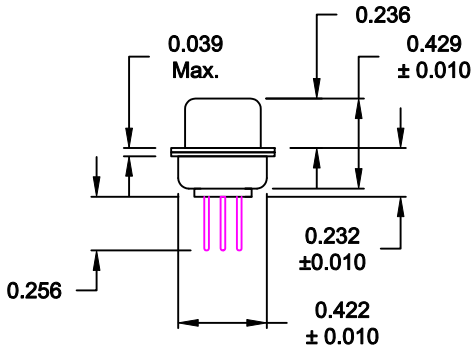
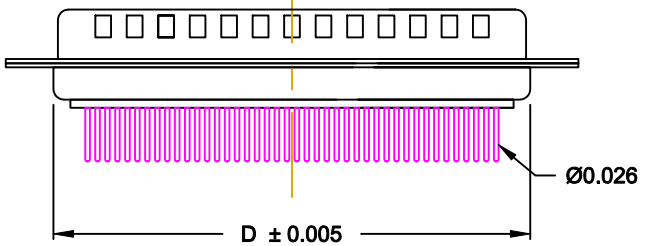
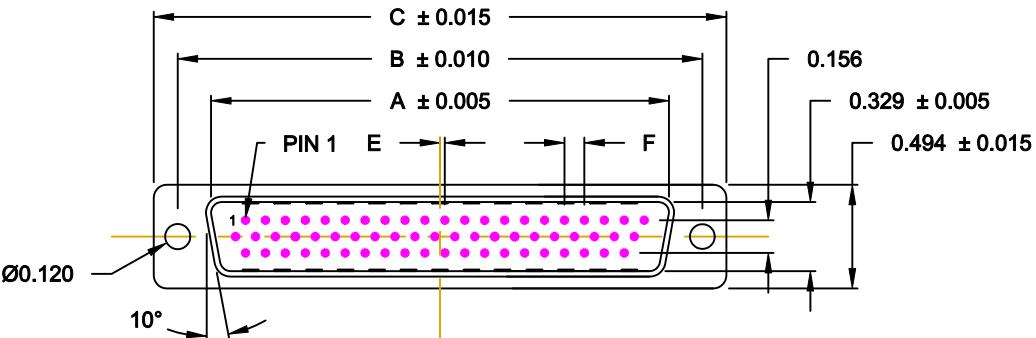
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Address: A1208, Overseas Decoration Building, #122 Zhenhua RD., Futian, Shenzhen, China



DESCRIPTION: MALE - HIGH DENSITY - MACHINED CONTACTS - VERTICAL



**MATERIALS AND FINISH:**

SHELL: STEEL MATERIAL, NICKEL FINISH  
 INSULATOR: PA6T = 260°C, UL 94V-0 RATED, BLACK  
 CONTACT MATERIAL: BRASS  
 CONTACT FINISH: FULL GOLD FLASH  
 SEAL MATERIAL: F08 FLEXIBLE ADHESIVE

**ELECTRICAL:**

CONTACT CURRENT RATING: 5 AMPS  
 CONTACT RESISTANCE: 30 Milliohms Max.  
 DIELECTRIC WITHSTANDING VOLTAGE: 1,000VAC Min.  
 INSULATION RESISTANCE: 5,000 Megohms Min.  
 TEMPERATURE RATING: -55° ~ +105° C

**780-M YY-1 1 3 R YY 1**

SERIES \_\_\_\_\_  
 MACHINED CONTACTS \_\_\_\_\_  
 POSITION \_\_\_\_\_  
 15 \_\_\_\_\_  
 26 \_\_\_\_\_  
 44 \_\_\_\_\_  
 GENDER \_\_\_\_\_  
 1 = MALE \_\_\_\_\_  
 TERMINATION \_\_\_\_\_  
 1 = VERTICAL DIP \_\_\_\_\_  
 SHELL PLATING \_\_\_\_\_  
 3 = NICKEL \_\_\_\_\_  
 RoHS COMPLIANT \_\_\_\_\_  
 HARDWARE \_\_\_\_\_  
 00 = Ø 0.120" HOLE (RECOMMEND PCB SPACER)  
 01 = 0.098" 4-40 INSERT, BOARD SIDE  
 05 = 0.224" 4-40 BOARD LOCK, BOARD SIDE  
 CONTACT PLATING \_\_\_\_\_  
 1 = GOLD FLASH, ENTIRE CONTACT  
 2 = 30 MICRO INCH GOLD  
 3 = 50 MICRO INCH GOLD

DIMENSIONS (IN.)						
No. OF PINS	A	B	C	D	E	F
15	0.666	0.984	1.213	0.759	0.010	0.090
26	0.994	1.312	1.541	1.083	0.020	0.090
44	1.534	1.852	2.088	1.625	0.020	0.090

**MEETS IP67 STANDARDS**

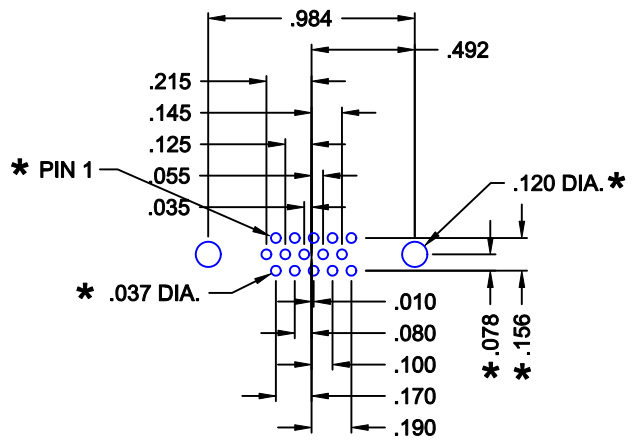
(SEE PAGE 3 FOR SEALING DETAILS)

**DO NOT SCALE FROM DRAWING**

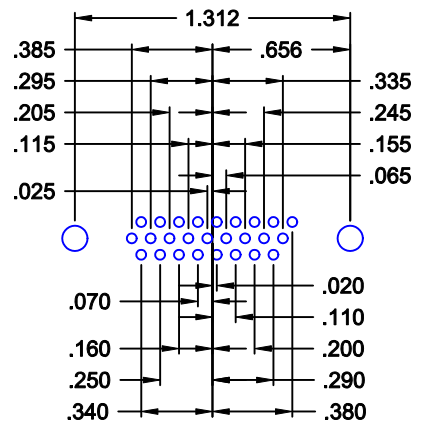
**RoHS COMPLIANT**

	THESE DRAWINGS AND SPECIFICATIONS ARE THE PROPERTY OF NorComp AND SHALL NOT BE REPRODUCED, COPIED OR USED AS THE BASIS FOR THE MANUFACTURE OF SALE OF APPARATUS WITHOUT WRITTEN PERMISSION.		DRAWN: <b>P. JENKINS</b>	DATE: <b>06-08-09</b>
			CHECKED:	DATE:
<b>NorComp</b>	SCALE: <b>1 : 1</b>	SHEET <b>1</b>	OF <b>4</b>	REV <b>9</b>
	DWG NO. <b>780-MYY-113RYY1</b>			

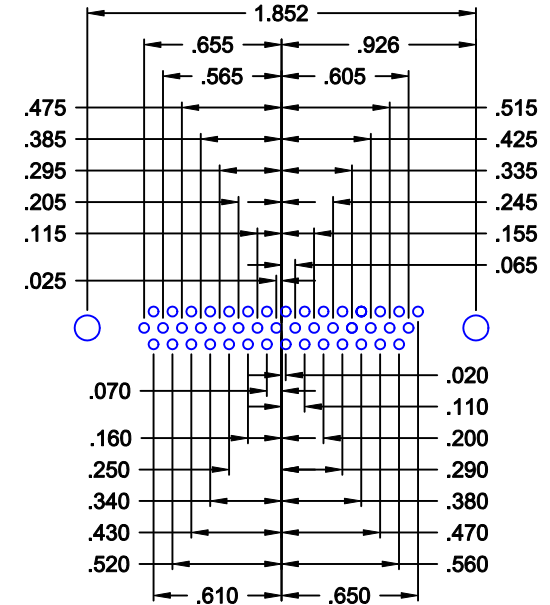
DESCRIPTION: LAYOUT - HIGH DENSITY - MACHINED CONTACTS - VERTICAL



15 POSITION




26 POSITION



44 POSITION

\* TYP. ON ALL SIZES

DO NOT SCALE FROM DRAWING

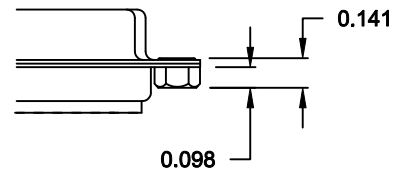
	THESE DRAWINGS AND SPECIFICATIONS ARE THE PROPERTY OF NorComp AND SHALL NOT BE REPRODUCED, COPIED OR USED AS THE BASIS FOR THE MANUFACTURE OF SALE OF APPARATUS WITHOUT WRITTEN PERMISSION.		DRAWN: <b>P. JENKINS</b>	DATE: <b>06-08-09</b>
			CHECKED:	DATE:
<h1>NorComp</h1>		SCALE: 1 : 1	SHEET 2 OF 4	REV 9
		DWG NO. <b>780-MYY-113RYY1</b>		

DESCRIPTION: CLINCH NUT HARDWARE

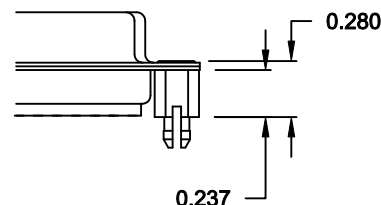
TOLERANCE:  
ALL DIMENSIONS ARE ±0.010

ALL CLINCH-NUTS ARE 4-40 INTERNAL THREADS


01X ..... 0.098" (BOARD SIDE) - CN1



05X ..... 0.237" BOARD SIDE - CN10

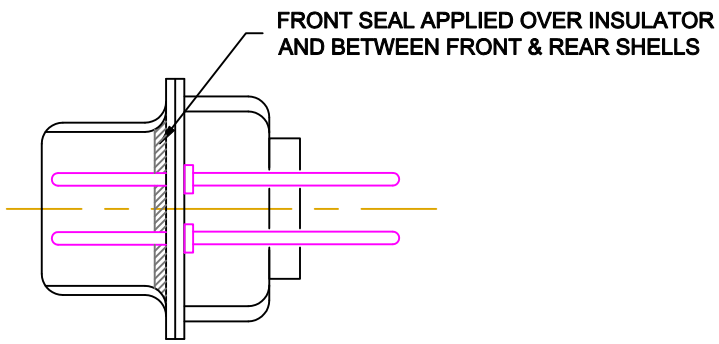
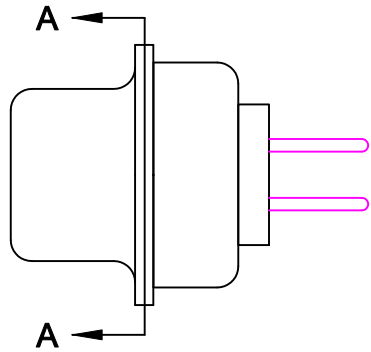


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			CHECKED:	DATE:
<h1>NorComp</h1>		SCALE:	SHEET <b>3</b>	OF <b>4</b>
		DWG NO. <b>780-MYY-113RYY1</b>		


RoHS COMPLIANT

DESCRIPTION: IP67 - MALE - HIGH DENSITY - DIP SOLDER - MACHINED - SEALING PROCESS



DETAIL A-A

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		CHECKED:	DATE:	
<b>NorComp</b>	SCALE: <b>2.5 : 1</b>	SHEET <b>4</b>	OF <b>4</b>	REV <b>9</b>
	DWG NO. <b>780-MYY-113RYY1</b>			